

MULTI-INNO TECHNOLOGY CO., LTD.

www.multi-inno.com

TOUCH PANEL SPECIFICATION

Model : MI0570KP-C

For Customer's Acceptance:

Customer		
Approved		
Comment		

Revision	1.2
Engineering	
Date	2013-04-01
Our Reference	



REVISION RECORD

REV NO.	REV DATE	CONTENTS	REMARKS
1.0	2012-03-06	Initial Release	
1.1	2012-12-26	Change IC	
1.2	2013-04-01	Change the CTP parameters	



Table of Contents

1.	COVER & CONTENTS	1
2.	RECORD OF REVISION	2
3.	APPLICATION	4
4.	GENERAL SPECIFICATIONS	4
5.	ABSOLUTE MAXIMUM RATINGS	4
6.	ELECTRICAL CHARACTERISTIC······	5
7.	TIMING SPECIFICATIONS	5
8.	PIN CONNECTIONS	8
9.	BLOCK DIAGRAM·····	8
	APPERANCE SPECIFICATION	
	QUALITY ASSURANCE	
	PRECAUTIONS IN USE CTP	
13.	OUTLINE DRAWING	14



3. APPLICATION

DVD player, UMPC, POS, MID

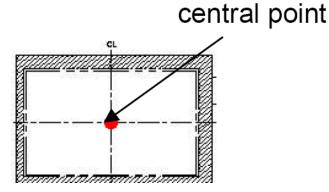
4. GENERAL SPECIFICATIONS

Composition: 5.7inch Capacitive Touch Panel (CTP). Interface: I^2C for the CTP.

ltem	Specification	Unit
Туре	Transparent type projected capacitive touch panel	
Input mode	Human's finger	
Finger	10	
Sensor Active Area	118.76(W)(typ.) x89.95(H)(typ.)	mm
Transparency	≧85%	%
Haze	≦2.0%	%
Origin Point	The upper left corner	
Hardness	7H (typ.) [by JIS K5400]	Pencil hardness
Report rate	Max: 122	Points/sec
Response time	15	ms
Point hitting life time	1,000,000 times min.	Note 1

Note 1: Use 8 mm diameter silicon rubber/force 3N to knock on the same point twice per

second (no-operating), after test function check pass.



5. ABSOLUTE MAXIMUM RATINGS

Symbol	Description Min		Тур.	Max	Unit	Notes
VCC1	Supply voltage	2.66	-	3.47	V	
VIO	DC input voltage	0	-	VCC1+0.3	V	



6. ELECTRICAL CHARACTERISTICS

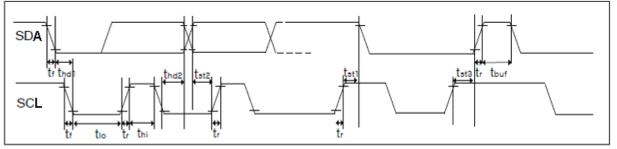
Symbol	Description	Min	Тур	Max	Unit	Notes
VCC1	Supply voltage	2.8	-	3.3	V	
GND	Supply voltage	-	0	-	V	
I	Active mode	-	13	15	mA	
Vih	Input H voltage	1.35	1.8	2.1	V	
VIL	Input L voltage	-0.3	0	0.45	V	

7. TIMING SPECIFICATIONS 7.1 CTP Interface and Data Format [Slave address is 0x5D(7 bit addressing)]

Communication protocol: I²C

Clock frequency : 100Khz (400Khz Fast mode)

Below is timing of I2C hardware circuit:



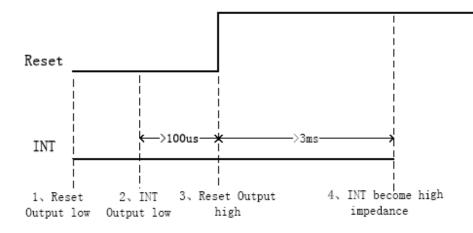
Test condition 1: 3.3V communication interface, 400Kbps, pull up resistor is 2K ohm

Parameter	Symbol	Min	Max	Unit
SCL low period	t _{lo}	0.9	0.9	us
SCL high period	t _{hi}	0.8	0.8	us
SCL setup time for START condition	t _{st1}	0.4	0.4	us
SCL setup time for STOP condition	t _{st3}	0.4	0.4	us
SCL hold time for START condition	t _{st1}	0.3	0.3	us
SDA setup time	t _{st2}	0.4	0.4	us
SDA hold time	t _{st2}	0.4	0.4	us

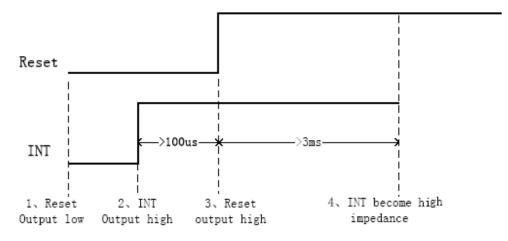
GT927 has 2 sets of slave address 0xBA/0xBB or 0x28/0x29. Master can control Reset & INT pin to configure the slave address the slave address in power on initial state like following



7.1.1 Timing of setting slave address to 0xBA/0XBB:



7.1.2 Timing of setting slave address to 0x28/0X29:



a) Data Transmission (ex: slave address is 0xBA/0xBB)

Communication is always initiated by master, A high-to-low transition of SDA with SCL high is a start condition.

All addresses words are serially transmitted to and from on bus in 8-bit words. GT927 sends a "0" to acknowledge when the address word is 0xBA/BB. This happens during the ninth clock cycle. If the slave address is not matched, GT927 will stay in idle state.

The data words are serially transmitted to and from in 9-bit words: 8-bit data + 1-bit ACK or NACK sent by GT927. Data changes during SCL high periods.

A low-to-high transition of SDA with SCL high is a stop condition. **b) Write Operations to GT927** (ex: slave address is 0xBA/0xBB)

s		A C K	Register_H	A C K	Register_L	A C K	Data_1	A C K		Data_n	A C K	Е	
---	--	-------------	------------	-------------	------------	-------------	--------	-------------	--	--------	-------------	---	--

Write Operations

Please check above figure, master start the communication first, and then sends address words 0XBA for a write operation.

After receiving ACK from GT927, master sends out register address word in 16-bit, and then the data word in 8-bit, which is going to be wrote into GT927.



GT927's address pointer will be automatically added 1 after write operation, so master can sequential write in one operation. When operation finished, master stop the communication.

c) Read Operations to GT927 (ex: slave address is 0xBA/0xBB)

s	Address_W	A C K	Register_H	A C K	Register_L	A C K	Е	S	Address_R	A C K	Data_1	A C K		Data_n	N E E
		►Se	t start register	addre	55 🗲						→ Re	ad dat	ta 🔶		

Read operation

Please check above figure, master start the communication first, and then sends address words 0xBA for a write operation.

After receiving ACK from GT927, master sends out register address word in 16-bit, to set GT927's address pointer. After receiving ACK, master sends out a start signal once again, start the read operation with command: 0xBB, and read data word from GT927 in 8-bit.

GT927 also supports sequential read operation, and the default setting is sequential read mode. Master shall send out ACK when receiving successfully in every data word, master sends NACK after getting all the data required, then sends stop signal to finish the communication.

7.1.3 Register Information of GT927

	ai nine Order (White On	y)									
Addr	Name	Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0		
0x8040	Command	0: read status of coordinate 1:D-value 2: software reset 3: benchmark update 4: benchmark calibration 5: screen off									
0x8041	LED_Control		Contro	l word u	nder co	ntrol of	touch ke	y LED lig	ght		
0x8042	Proximity_En	Proximity switch									

a) Real Time Order (Write Only)



· · · · ·	iguration information (,	_			_	_	_	_		
Addr	Name	Bit7	Bit6		Bit5	Bit4	Bit3	Bit2	Bit1	Bit0	
0x8047	Config_Version		V	ersic	on numl	per of c	onfigur	ation do	cument		
0x8048	X Output Max_L				M	ay valı	le of X	avis			
0x8049	X Output Max_H				IVI			0,15			
0x804A	Y Output Max_L				M	ax valı	ie of Y	avis			
0x804B	Y Output Max_H	Max value of Y axis									
0x804C	Touch Number	Reserved Touch number: 1~5									
0x804D	Module_Switch1	Rese	ved	Str	etch_ra	nk	X2Y	Sito	m	trigger ethod	
0x804E	Module_Switch2				erved				Fouch_K		
0x804F	Shake_Count		Re	eser					shake c		
0x8050	Filter	Firs	t_Filte	r					alue of o efficiency		
0x8051	Large_Touch				Numbe	er of tou	uch in la	arge are	a		
0x8052	Noise_Reduction		Rese	erved	l	Valu	ie of no	ise elim is '		coefficient	
0x8053	S_Touch_Level			Thre	eshold of	of toucl	grow	out of no	othing		
0x8054	S Leave Level							out of no			
0x8055	Low_Power_Control	Reserved Time to low power consumption(0~15									
0x8056	Refresh_Rate	Reserved Coordinate report rate(Cycle 5+N ms)									
0x8057	x threshold										
0x8058	y threshold					Res	served				
0x8059	X_Speed_Limit				Dare			al 11.00014			
0x805A	Y_Speed_Limit				Para	ameter	of spee				
0x805B	•				oarder-		Blank	area of	f boarde	r-bottom	
0x805C	Space	Blan	k area	of b	oarder-	left	Blar	nk area o	of board	er-right	
0x805D	NC					Res	served				
0x805E	NC						served				
0x805F	NC					Res	served				
0x8060	NC						served				
0x8061	NC						served				
0x8062	Drv_GroupA_Num	All_D	riving		Reserve				up_A_n		
0x8063	Drv_GroupB_Num		served		D_F				up_B_n		
0x8064	Sensor_Num				B_Num				pup_A_N		
0x8065	FreqA_factor	Driver							t of Drive *baseba	er group A nd	
0x8066	FreqB_factor	Driver							t of Drive *baseba	er group B nd	
0x8067	Pannel_BitFreqL	Baseband of Driver group A\B(1526Hz <baseband<14600hz)< td=""></baseband<14600hz)<>									
0x8068	Pannel_BitFreqH	Dase	band	ט וט	nver gro	Jup A\t	o(15∠01	⊐∠ <dase< td=""><td>spana<1</td><td>4000HZ)</td></dase<>	spana<1	4000HZ)	
0x8069	Pannel_Sensor_TimeL	т:	na int-	ma	of the r	aihaur	ing tur	drivéna	oignol/!	lait: ua)	
0x806A	Pannel_Sensor_TimeH	Time interval of the neibouring two driving signal(Unit: us)								mit: us)	

b) Configuration Information (R/W)



			Pannal	_Drv_outp	ut D		
0x806B	Pannel_Tx_Gain	Reserved		4 gears			nel_DAC_Gain
0x806C	Pannel_Rx_Gain	Pannel_PGA _C Pannel_PGA_R ^I		_Vo	el_Rx cmi	Pannel_PGA _Gain	
0x806D	Pannel_Dump_Shift	Reserved		ed Magnification coefficient of original value(The Nth power of 2)		0	
0x806E	Drv_Frame_Control	Reserved	S	SubFrame_Drv Num		Repeat_Num	
0x806F	NC			Reserv	ed		
0x8070	NC			Reserv			
0x8071	NC			Reserv			
0x8072	Stylus Tx Gain	Uno	defined(in	valid wher		priorit	v=0)
0x8073	Stylus_Rx_Gain			valid wher			
0x8074	Stylus_Dump_Shift			valid wher			
0x8075	Stylus_Touch_Level			valid wher			
0x8076	Stylus_Leave_Level			valid wher			
0x8077	Stylus Control			ape time o			
0x8078	NC		11000 000	Reserv		ou(onic	
0x8079	NC			Reserv	~~		
0x807A	Freq_Hopping_Start	Frequency	hopping		ency(U	nit: 2KH	Iz,50means
0x807B	Freq_Hopping_End	Frequency	hopping s		ncy(Un	it: 2KH	z,150means
0x807C	Noise_Detect_Tims	Detect_Stay_	Times			Confirm	_Times
0x807D	Hopping_Flag	Hop_En		eserved			Time Out
0x807E	Hopping_Threshold	Large Nois					Threshold
0x807F	Noise Threshold			eshold of n			
0x8080	NC			Reserv			
0x8081	NC	Reserved					
0x8082	Hopping_seg1_BitFreqL	Frequency	hoppina s			entral f	requency(for
0x8083	Hopping_seg1_BitFreqH	Frequency hopping segment band 1 central frequenc					
0x8084	Hopping_seg1_Factor	Frequency h	oppina se		,	requen	cy coefficient
0x8085	Hopping_seg2_BitFreqL	Frequency hopping segment band 2 central frequency(
0x8086	Hopping_seg2_BitFreqH	driver A/B)					
0x8087	Hopping_seg2_Factor	Frequency h	oppina se		,	requen	cy coefficient
0x8088	Hopping_seg3_BitFreqL						requency(for
0x8089	Hopping_seg3_BitFreqH	- 1	- TT - 5 -	driver A			
0x808A	Hopping_seg3_Factor	Frequency h	opping se	egment 3 c	central f	requen	cy coefficient
0x808B	Hopping_seg4_BitFreqL						requency(for
0x808C	Hopping_seg4_BitFreqH	1) -		driver A			
0x808D	Hopping_seg4_Factor	Frequencv h	opping se		,	requen	cy coefficient
0x808E	Hopping_seg5_BitFreqL						requency(for
0x808F	Hopping_seg5_BitFreqH	- -	11 .30	driver A			1 - 2 (
0x8090	Hopping_seg5_Factor	Frequency h	oppina se			reauen	cy coefficient
0x8091	NC	ctor Frequency hopping segment 5 central frequency coe Reserved					
0x8092	NC			Reserv			
0x8093	Key1	Key 1 Position: 0~255 valid(0 means no touch, it means independent touch key when 4 of the keys are 8 multiples)					
0x8094	Key2	Key 2 position		/ /			
0x8095	Key3	Key 3 position					
0x8096	Key4	Key 4 position					
0x8097	Key_Area	Time limit for long press(1~16s) Touch valid interval setti 0~15 valid					
0x8098	Key_Touch_Level						
0,0030							



0x8099	Key_Leave_Level		Key threshold	of touch ke	ΞV
	•	Key threshold of touch key KeySens_1(sensitivity coefficient of key KeySens			
0x809A	Key_Sens	1,same below) KeySens		KeySens_2	
0x809B	Key_Sens	KeySens_3 KeySens_4		KeySens_4	
0x809C	Key_Restrain	Reserved Reserved			
0x809D	NC		Reser	ved	
0x809E	NC		Reser	ved	
0x809F	NC		Reser	ved	
0x80A0	NC		Reser	ved	
0x80A1	NC		Reser	ved	
0x80A2	Proximity_Drv_Select	driving d			rv_End_Ch(End channel)
0x80A3	Proximity_Sens_Select	sensing of	(start channel of direction)		ns_End_Ch(End channel)
0x80A4	Proximity_Touch_Level		oximity effective		
0x80A5	Proximity_Leave_Level		ximity ineffective		
0x80A6	Proximity_Freq_Factor	Frequency	mollification of p	roximity se	ensing channel
0x80A7	Proximity_BitFreqL	Base fre	equency of proxi	mitv sensi	ng channel
0x80A8	Proximity_BitFreqH	Babbin			
0x80A9	Proximity_Sensor_TimeL				
0x80AA	Proximity_Sensor_Time H	Time interval between proximity adjacent driving signal			
0x80AB	Proximity_Tx_Gain		Driving gain o		
0x80AC	Proximity_Rx_Gain		Driving gain o		
0x80AD	Proximity_Dump_Shift	Reserved Magnification coefficient of proximity ori value(The Nth power of 2)			
0x80AE	NC	Reserved			
0x80AF	NC		Reser	ved	
0x80B0	NC	Reserved			
0x80B1	NC		Reser	ved	
0x80B2	NC		Reser	ved	
0x80B3	NC		Reser	ved	
0x80B4	NC		Reser	ved	
0x80B5	NC		Reser		
0x80B6	NC	Reserved			
0x80B7~	Sensor_CH0~	Correc	sponding change	al no of IT	O Sensor
0x80C4	Sensor_CH13	Corresponding channel no. of ITO Ser			
0x80C5~	NC		Reser	ved	
0x80D4		Corresponding channel no. of ITO Driver0			
0x80D5~	Driver_CH1~			O Driver0	
0x80EA	Driver_CH21				
0x80EB~	NC	Reserved			
0x80FE				nation	
0x80FF	Config_Chksum	Check of configuration information Updated configuration(by master control)			
0x8100	Config_Fresh	Updai	eu coniiguration	itby maste	



bit6 Addr bit7 bit5 bit4 bit3 bit2 bit1 bit0 0x8140 Product ID(Lowest Byte, ASCII code 6) 0x8141 Product ID(Third Byte, ASCII code 0) Product ID(Second Byte, ASCII code 0) 0x8142 0x8143 Product ID(Highest Byte, ASCII code 9) 0x8144 Firmware version(byte1)(Low Byte) Firmware version(byte2)(High Byte) 0x8145 x coordinate resolution(low byte)(current output resolution) 0x8146 0x8147 x coordinate resolution(high byte) y coordinate resolution(low byte) 0x8148 y coordinate resolution(high byte) 0x8149 Vendor_id(current module choice information) 0x814A Reserved 0x814B 0x814C gesture type(Reserved) 0x814D gesture value(Reserved) buffer Large 0x814E **Proximity Valid** HaveKey number of touch points status detect 0x814F track id 0x8150 point 1 x coordinate(low byte) 0x8151 point 1 x coordinate(high byte) 0x8152 point 1 y coordinate(low byte) 0x8153 point 1 y coordinate(high byte) 0x8154 point 1 size(low byte) 0x8155 point 1 size(high byte) 0x8156 Reserved 0x8157 track id point 2 x coordinate(low byte) 0x8158 0x8159 point 2 x coordinate(high byte) 0x815A point 2 y coordinate(low byte) 0x815B point 2 y coordinate(high byte) 0x815C point 2 size(low byte) point 2 size(high byte) 0x815D 0x815E Reserved track id 0x815F point 3 x coordinate(low byte) 0x8160 0x8161 point 3 x coordinate(high byte) 0x8162 point 3 y coordinate(low byte) 0x8163 point 3 y coordinate(high byte) 0x8164 point 3 size(low byte) 0x8165 point 3 size(high byte) 0x8166 Reserved 0x8167 track id 0x8168 point 4 x coordinate(low byte) 0x8169 point 4 x coordinate(high byte) 0x816A point 4 y coordinate(low byte) 0x816B point 4 y coordinate(high byte) 0x816C point 4 size(low byte) point 4 size(high byte) 0x816D 0x816E Reserved 0x816F track id 0x8170 point 5 x coordinate(low byte) 0x8171 point 5 x coordinate(high byte) 0x8172 point 5 y coordinate(low byte)



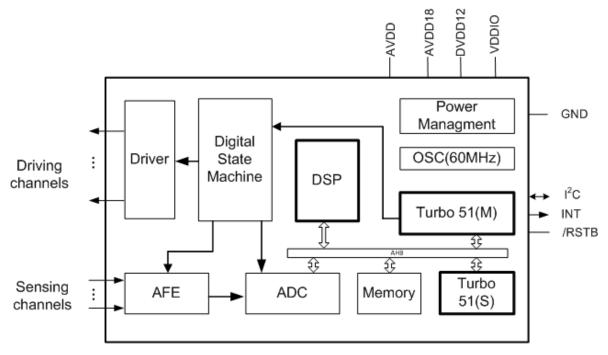
0x8173	point 5 y coordinate(high byte)	
0x8174	point 5 size(low byte)	
0x8175	point 5 size(high byte)	
0x8176	Reserved	
0x8177	track id	
0x8178	point 6 x coordinate(low byte)	
0x8179	point 6 x coordinate(high byte)	
0x817A	point 6 y coordinate(low byte)	
0x817B	point 6 y coordinate(high byte)	
0x817C	point 6 size(low byte)	
0x817D	point 6 size(high byte)	
0x817E	Reserved	
0x817F	track id	
0x8180	point 7 x coordinate(low byte)	
0x8181	point 7 x coordinate(high byte)	
0x8182	point 7 y coordinate(low byte)	
0x8183	point 7 y coordinate(high byte)	
0x8184	point 7 size(low byte)	
0x8185	point 7 size(high byte)	
0x8186	Reserved	
0x8187	track id	
0x8188	point 8 x coordinate(low byte)	
0x8189	point 8 x coordinate(high byte)	
0x818A	point 8 y coordinate(low byte)	
0x818B	point 8 y coordinate(high byte)	
0x818C	point 8 size(low byte)	
0x818D	point 8 size(high byte)	
0x818E	Reserved	
0x818F	track id	
0x8190	point 9 x coordinate(low byte)	
0x8191	point 9 x coordinate(high byte)	
0x8192	point 9 y coordinate(low byte)	
0x8193	point 9 y coordinate(high byte)	
0x8194	point 9 size(low byte)	
0x8195	point 9 size(high byte)	
0x8196	Reserved	
0x8197	track id	
0x8198	point 10 x coordinate(low byte)	
0x8199	point 10 x coordinate(high byte)	
0x819A	point 10 y coordinate(low byte)	
0x819B	point 10 y coordinate(high byte)	
0x819C	point 10 size(low byte)	
0x819D	point 10 size(high byte)	
0x819E	Reserved	
0x819F	Keyvaule	



8. Pin Connections

No.	Name	I/O	Description
1	NC	-	No connection
2	SCL	Ι	I ² C Clock
3	SDA	I/O	I ² C Data
4	NC	-	No connection
5	INT	0	Interrupt output
6	GND	Р	Ground
7	VCC1	Р	Power supply Voltage
8	/RESET	I	Reset active low
9	NC	-	No connection

9. BLOCK DIAGRAM





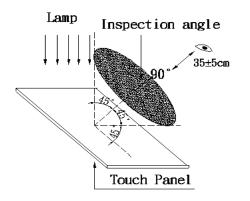
10. Appearance Specification

10.1 Process/Content:

- 10.1.1Inspection equipment : fluorescent lamp · functional test jig · magnifying glass, Vernier caliper, ESD wrist strap.
- 10.1.2 Environment demand
 - 1.2.1 Temperature : $25\pm5^{\circ}$ C
 - 1.2.2 Humidity : 30-75%RH
 - 1.2.3 Luminance : Fluorescent light (appearance : 800-1200UXL function : 100-500UXL)
- 10.1.3 Inspection process
 - 1.3.1 Inspect distribution operation
 - 1.3.2 Shift team leader is in charge of distributing work when work order goes to OQC inspection of finished products
 - 1.3.3 Products of great emergency or especially asked by customer should be finished in advance.
 - 1.3.4 All the items should be fully inspected before shipment.
 - 1.3.5 The inspection standard & specification should be carried out according to customer's demand. If customer has no other standard & specification, just stick to this one.
- 10.1.4 Sampling plan
 - 1.4.1 Do tests regularly according to MIL-STD-105E. Single sampling plan is arrived out according to Level.
 - 1.4.2 Defect definition
 - 1.4.2.1 Major defect is inspected according to AQL 0.40%.
 - 1.4.2.2 Minor defect is inspected according to AQL 0.40%.

10.1.5 Appearance inspection

- 1.5.1 Appearance inspection method
 - Inspection angle spacing : 30-40cm





1.5.2 Appearance inspection standard

ltem	Spec		Statement
	Spec	Q'ty allowed	
Foreign material	D>0.5mm	0	
Punctiform	0.3mm≦D≦0.5mm	5	D= (L + W) / 2
	D<0.3mm	Di sregarded	
	Spec	Q'ty allowed	
	W>0.1mm L>5mm	0	
Foreign material Linear	0.05mm≦W≦ 0.1mm L≦5mm	5	L : Long W : Width
	₩<0.05mm	Di sregarded	
Image uniformity	Gray color can b through		

	Spec	Q'ty allowed	\sim
TP scratch	W>0.07mm L>7mm	0	
	W≦0.07mm L≦7mm	5	L
TP dented spot	Spec	Q'ty allowed	
	D>0.5mm	0	L D= (L + W) / 2
	0.3mm≦D≦0.5mm	5	
TP overflows or lacks of glue	±0.45mm		



Surface broken	X<2mm Y<2mm Z <glass< td=""><td></td></glass<>	
Edge broken	X<2mm Y<2mm Z <glass< td=""><td></td></glass<>	
Rift	Not allowed	VY-
Bubble appears in protection film	D>10mm N=O 5≦D≦10mm N=2 D<5 disregarded	
TP deviation	According to the specifications of customer's drawing	
Bubbl e	$D \le 0.2mm$ disregarded $0.2mm < D \le 0.3mm$ $N \le 2$ 0.3mm < D not allowed No influence on appearance and function in invisible area OK	
Printing ink	No light leak Silk-screen saw tooth : S≦0.1 disregarded O.1mm≦S≦O.15mm N=5 S>O.15 ng LOGO break line NG Script dim, printed backwards , no printing in wrong place	
Finger print	Not allowed	
Stain	Stain on surface can be removed OK Bonding surface has no influence on appearance and function OK Can't be removed & not allowed	
Protection film	Bent isn't allowed No lift up Bent is allowed L<10MM N≦5	



11. QUALITY ASSURANCE

11.1 Test Condition

- 11.1.1 Temperature and Humidity (Ambient Temperature) Temperature: $25 \pm 5^{\circ}C$ Humidity: $65 \pm 5\%$
- 11.1.2 Operation

Unless specified otherwise, test will be conducted under function state.

11.1.3 Container

Unless specified otherwise, vibration test will be conducted to the product itself without putting it in a container.

11.1.4 Test Frequency

In case of related to deterioration such as shock test. It will be conducted only once.

	Reliability Test Item & Level	Test Level
No.	Test Item	
1.	High Temperature Storage Test	T = $80^{\circ}_{,C}$ 120hrs after 1 hrs at room temperature and test.
2.	Low Temperature Storage Test	T = -30, C 120 hrs after 1 hrs at room temperature and test.
3.	High Temperature and High Humidity Storage Test	T= 40° C , 90%RH,120hrs after 24 hrs at room temperature and test.
4.	Thermal Cycling Test (No operation)	-30 $^\circ\!{\rm C}$ 30min ~ 80 $^\circ\!{\rm C}$ 30 min , 100 Cycles after 24 hrs at room temperature and test.
5.	Vibration Test (No operation)	Frequency :10 ~ 55 HZ Amplitude :1.5 mm Sweep time : 11 mins Test Period: 6 Cycles for each direction of X, Y, Z
6.	ESD TEST	Air Discharge:±15KV Indirect Contact Discharge:±8KV

11.1.5 Test Method



12. PRECAUTIONS IN USE CTP

1. EMBLY PRECAUTIONS

- Since Touch Panel is consist of glass, please be careful your hands to be injured during handing. You must wear gloves during handing.
- (2) Do not touch, push or rub the exposed touch panel, tweezers or anything harder than HB pencil lead. And please do not rub with dust clothes with chemical treatment.
- (3) Do not stack the touch panels together.Do not put heavy objects on touch panel.
- (4) Please do not take a CTP to pieces and reconstruct it. Resolving and reconstructing modules may cause them not to work well.
- (5) Please excessive force or strain to the panel or tail is prohibited, Do not lift touch panel by cable (FPC).
- (6) Use clean sacks or glove to prevent fingerprints and/or stains left on the panel. Extra attention and carefulness should be taken while handling the glass edge.
- (7) Please pay attention for the matters stated below at mounting design of touch panel enclosure. Enclosure support to fix touch panel must be out of active area.(do not design enclosure presses the active area to protect from miss put)
- 2. RATING PRECAUTIONS
 - (1) Please be sure to turn off the power supply before connecting and disconnecting signal input cable.
 - (2) Please do not change variable resistance settings in CTP. They are adjusted to the most suitable value. If they are changed, it might happen CTP does not satisfy the characteristics specification
 - (3) Be careful for condensation at sudden temperature change. Condensation makes damage to snesor or electrical contacted parts.
 - (4) CTP has high frequency circuits. Sufficient suppression to the electromagnetic interference shall be done by system manufacturers. Grounding and shielding methods may be important to minimize the interference.
 - (5) Touch the panel with your finger or stylus only to assure normal operation. Any sharp edged or hard objects are prohibited.
 - (6) Operate the panel in a steady environment. Abrupt variation on temperature and humidity may cause malfunction of the panel.
- 3. ELECTROSTATIC DISCHARGE CONTROL
 - (1) The operator should be grounded whenever he/she comes into contact with the CTP. Never touch any of the conductive parts such the copper leads on the FPC and the interface terminals with any parts of the human

- (2) The CTP should be kept in antistatic bags or other containers resistant to static for storage.
- (3) Only properly grounded soldering irons should be used.
- (4) If an electric screwdriver is used, it should be well grounded and shielded from commutator sparks.
- (5) The normal static prevention measures should be observed for work clothes and working benches; for the latter conductive (rubber) mat is recommended
- (6) Since dry air is inductive to statics, a relative humidity of 50-60% is recommended.

4. STORAGE PRECAUTIONS

- (1) When you store touch panel for a long time, it is recommended to keep the temperature between 0°C-40°C without the exposure of sunlight and to keep the humidity less than 90%RH.
- (2) Please do not leave touch panel in the environment of high humidity and high temperature such as 60°C 90%RH
- Please do not leave touch panel in the environment of low temperature; below -20°C.
- 5. OTHERS
 - For the packaging box, please pay attention to the followings:
 - a. Please do not pile them up more than 5 boxes. (They are not designed so.) And please do not turn over.
 - b. Please handle packaging box with care not to give them sudden shock and vibrations. And also please do not throw them up.
 - c. Packing box and inner case for CTP are made of cardboard. So please pay attention not to get them wet. (Such like keeping them in high humidity or wet place can occur getting them wet.)

6. LIMITED WARRANTY

Unless otherwise agreed between MULTI-INNO and customer, MULTI-INNO will replace or repair any of its CTP which is found to be defective electrically and visually when inspected in accordance with MULTI-INNO acceptance standards, for a period on one year from date of shipment. Confirmation of such date shall be based on freight documents. The warranty liability of MULTI-INNO is limited to repair and/or replacement on the terms set forth above. MULTI-INNO will not responsible for any subsequent or consequential events.



13. OUTLINE DRAWING

